TT6KF THRU TT6MF

Voltage Range - 800 to 1000 Volts Current - 6.0 Ampere

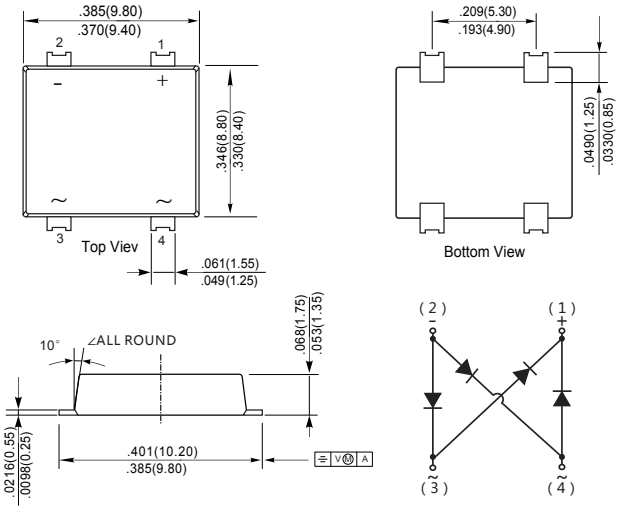
GLASS PASSIVATED SURFACE MOUNT BRIDGE RECTIFIERS

Features

TTF

RoHS COMPLIANT

- Glass Passivated Chip Junction
- Reverse Voltage - 800 to 1000 V
- Forward Current- 6.0 A
- High Surge Current Capability
- Designed for Surface Mount Application



Dimensions in inches and (millimeters)

Mechanical Data

Case : JEDEC TTF molded plastic body
Terminals : Solderable per MIL-STD-750,Method 2026
Polarity : Polarity symbol marking on body Mounting Position : Any
Weight : 0.0163 ounce, 0.461 grams

Maximum Ratings And Electrical Characteristics

Ratings at 25℃ ambient temperature unless otherwise specified.
Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%.

Parameter	Symbols	TT6KF	TT6MF	Units
Marking Code		MDD TT6KF	MDD TT6MF	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	800	1000	V
Maximum RMS voltage	V_{RMS}	560	700	V
Maximum DC Blocking Voltage	V_{DC}	800	1000	V
Maximum Average Forward Rectified Current	I_O	6		A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	200		A
I^2t Rating for Fusing	I^2t	166		A^2S
Maximum Forward Voltage at 1.0 A	V_F	0.83 typ.		V
Maximum Forward Voltage at 6.0 A	V_F	1.0		V
Maximum DC Reverse Current @T_a=25 °C at Rated DC Blocking Voltage @T_a=125 °C	I_R	5 100		μA
Typical Junction Capacitance (Note1)	C_j	60		pF
Typical Thermal Resistance (Note2)	$R_{\theta JA}$ $R_{\theta JC}$ $R_{\theta JL}$	60 10 12		°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150		℃

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. P.C.B. mounted with 4×1.5"×1.5" (3.81×3.81 cm) copper pad areas.

DN:T19B27A0

Typical Characterisitics

Fig.1 Average Rectified Output Current Derating Curve

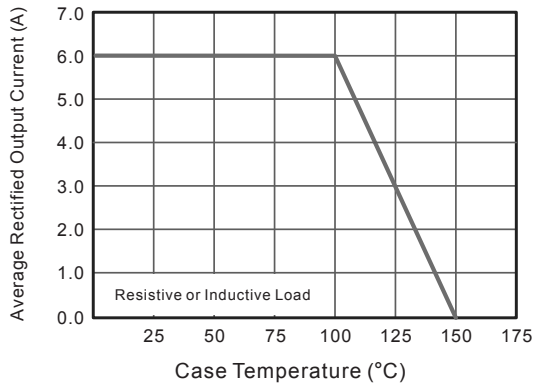


Fig.2 Typical Reverse Characteristics

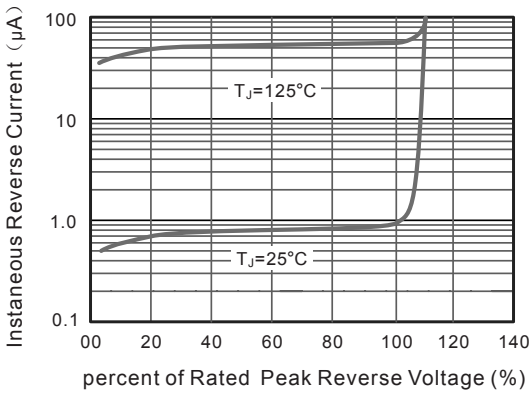


Fig.3 Typical Instaneous Forward Characteristics

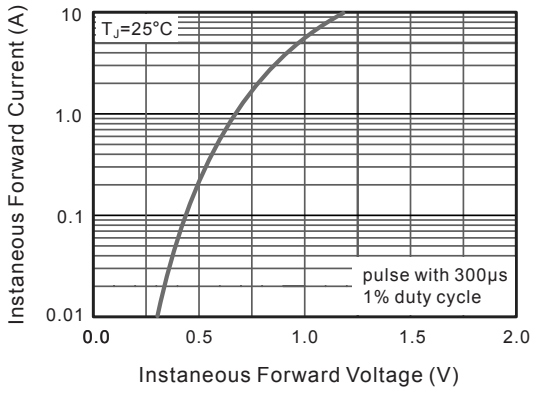


Fig.4 Typical Junction Capacitance

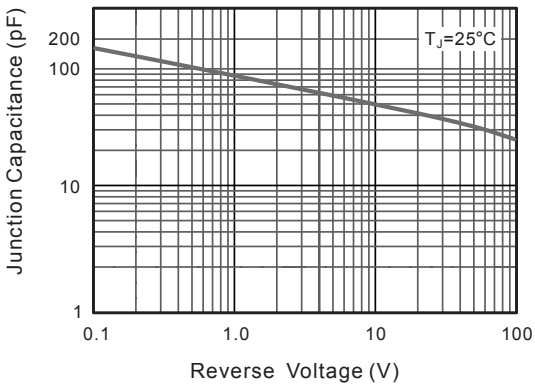


Fig.5 Maximum Non-Repetitive Peak Forward Surage Current

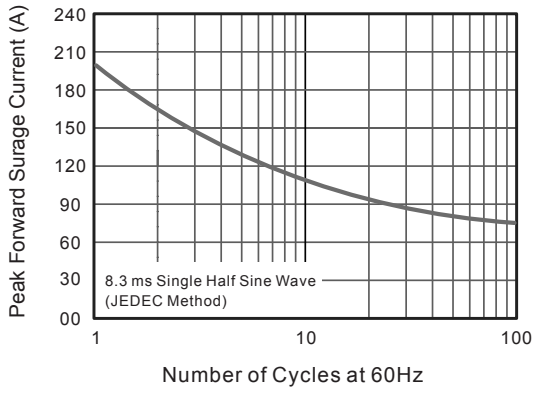
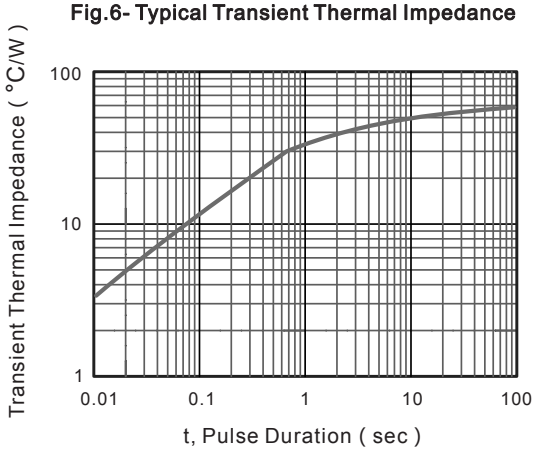
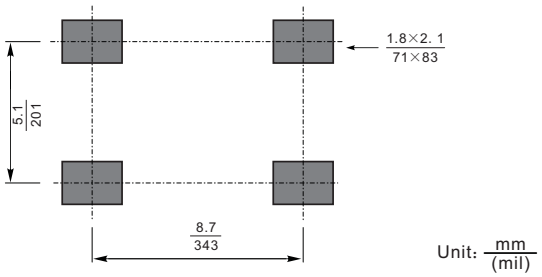


Fig.6- Typical Transient Thermal Impedance



The curve above is for reference only.

Suggested Pad Layout



Note:
1.Controlling dimension:in/millimeters.
2.General tolerance: ±0.05mm.
3.The pad layout is for reference purposes only.

Important Notice and Disclaimer

Microdiode Electronics (Jiangsu) reserves the right to make changes to this document and its products and specifications at any time without notice. Customers should obtain and confirm the latest product information and specifications before final design,purchase or use.

Microdiode Electronics (Jiangsu) makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, not does Microdiode Electronics (Jiangsu) assume any liability for application assistance or customer product design. Microdiode Electronics (Jiangsu) does not warrant or accept any liability with products which are purchased or used for any unintended or unauthorized application.

No license is granted by implication or otherwise under any intellectual property rights of Microdiode Electronics (Jiangsu).

Microdiode Electronics (Jiangsu) products are not authorized for use as critical components in life support devices or systems without express written approval of Microdiode Electronics (Jiangsu).